



INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION
Generic Copy

28-MAY-2004

SUBJECT: ON Semiconductor Initial Product/Process Change Notification #13480

TITLE: Qualification of XFAB Texas Wafer Fab for NCP2890A Micro-Bumped Devices

EFFECTIVE DATE: 28-Sep-2004

AFFECTED CHANGE CATEGORY:
Subcontractor Fab Site

AFFECTED PRODUCT DIVISION:
Analog Products

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact Sales Office or Todd Manes <RP06650@onsemi.com>

NOTIFICATION TYPE:
Initial Product/Process Change Notification (IPCEN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 60 days prior to implementation of the change.

DESCRIPTION AND PURPOSE:

This is an initial PCN announcing ON Semiconductor is qualifying the XFAB Texas wafer fab facility located in Lubbock, Texas as an additional source for NCP2890A micro-bumped devices. X-fab Texas is certified: ISO9001 : 2000 ISO TS 16949 VDA 6.1 QS9000. The device will continue to be assembled and tested at existing, qualified locations. XFAB offers the same process technology in both fab locations; therefore, no die design changes will be made and no changes in electrical performance of the device are anticipated. No device specifications will change as a result of this additional wafer fab qualification.

**Initial Product/Process Change Notification #13480****QUALIFICATION PLAN:**

This device family is available with standard solder composition and with Pb-Free solder composition. Qualification testing will be performed on both device types. Testing will consist of:
Temperature Cycling from -40C to +125C for 500 cycles with additional information at 1000 cycles.
Temperature Cycling will be performed on 1 lot of each solder composition type.
Electrical characterization data will be taken over the operating temperature range of -40C to +85C.
Characterization data will be taken on devices from 2 wafer lots.
ESD and Latch-Up data will be taken on devices from 1 wafer lot.
Solder Ball Shear data will be taken on devices with each solder composition type and from two separate wafer lots.

AFFECTED DEVICE LIST (WITHOUT SPECIALS):**PART**

NCP2890AFCT2

NCP2890AFCT2G